**UD Package**

16-Lead Plastic QFN (3mm x 3mm)

(Reference LTC DWG # 05-08-1700 Rev A)

Exposed Pad Variation AA

**RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS**

- 3.00 ± 0.10 (4 SIDES)
- 1.65 ± 0.10 (4 SIDES)

**NOTE:**

1. Drawing conforms to JEDEC Package Outline MO-220 Variation (WEED-4)
2. Drawing not to scale
3. All dimensions are in millimeters
4. Dimensions of exposed pad on bottom of package do not include mold flash. Mold flash, if present, shall not exceed 0.15mm on any side
5. Exposed pad shall be solder plated
6. Shaded area is only a reference for Pin 1 location on the top and bottom of package